Amendments to the Claims:

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

Please amend the claims as shown:

1. (Currently Amended) An epoxy resin composition for encapsulating of semiconductors which is used for ~~so-called~~ area mounting [[type]] semiconductor devices formed by mounting semiconductor elements on one side of a printed circuit board or a metallic lead frame and encapsulating with a resin substantially only the side on which the semiconductor elements are mounted, and which comprises (A) an epoxy resin, (B) a phenolic resin, (C) a curing accelerator and (D) an inorganic filler as main components, characterized in that properties of a cured product formed by heating and curing the epoxy resin composition satisfy expressions, $a \geq 10^R$ ($R=10\times(b+c)-1$, $300 \leq a \leq 20000$ and $0.15 \leq b+c \leq 0.50$ in which a denotes a flexural modulus (N/mm^2) at molding temperature, b denotes a cure shrinkage (%) and c denotes a heat shrinkage (%) of from molding temperature to room temperature, and the value "a" is measured in accordance with JIS K 6911 and the value "b+c" is calculated from the formula

$$\frac{\left(\begin{array}{c}\text{inner diameter of the}\\ \text{mold cavity at 175°C}\end{array}\right) - \left(\begin{array}{c}\text{outer diameter of the}\\ \text{disk cured product at 25°C}\end{array}\right)}{\left(\begin{array}{c}\text{inner diameter of the}\\ \text{mold cavity at 175°C}\end{array}\right)} \times 100$$

2. (Original) An epoxy resin composition for encapsulating of semiconductors according to claim 1, wherein the cured product has a moisture absorption rate of not more than

0.20% by weight after treated for 168 hours in an environment of 85°C and 60% in relative humidity.

3. (Previously Presented) An epoxy resin composition for encapsulating of semiconductors according to claim 1 wherein the epoxy resin and/or the phenolic resin have/has a naphthalene skeleton.

4. (Previously Presented) A semiconductor device obtained by encapsulating with the epoxy resin composition according to claim 1.

5. (Previously Presented) An epoxy resin composition for encapsulating of semiconductors according to claim 2 wherein the epoxy resin and/or the phenolic resin have/has a naphthalene skeleton.

6. (Previously Presented) A semiconductor device obtained by encapsulating with the epoxy resin composition according to claim 2.

7. (Previously Presented) A semiconductor device obtained by encapsulating with the epoxy resin composition according to claim 3.

8. (Currently Amended) An epoxy resin composition for encapsulating of semiconductors according to claim 1, wherein the epoxy resin (A) comprises a biphenyl [[type]] epoxy resin, and the phenolic resin (B) comprises a phenolic aralkyl resin and/or naphthol aralkyl resin.

9. (Currently Amended) An epoxy resin composition for encapsulating of semiconductors according to claim 2, wherein the epoxy resin (A) comprises a biphenyl [[type]] epoxy resin, and the phenolic resin (B) comprises a phenolic aralkyl resin and/or naphthol aralkyl resin.

10. (Previously Presented) An epoxy resin composition for encapsulating of semiconductors according to claim 1, wherein the epoxy resin (A) comprises an epoxy resin having a naphthalene backbone, and the phenolic resin (B) comprises a naphthol aralkyl resin.

11. (Previously Presented) An epoxy resin composition for encapsulating of semiconductors according to claim 2, wherein the epoxy resin (A) comprises an epoxy resin having a naphthalene backbone, and the phenolic resin (B) comprises a naphthol aralkyl resin.

12. (Withdrawn) A method for encapsulating a semiconductor comprising mounting a semiconductor element on one side only of a printed circuit board or a metallic lead frame and encapsulating with an epoxy resin composition substantially only on the side of the printed circuit board on which the semiconductor element is mounted, said epoxy resin composition comprising (A) an epoxy resin, (B) a phenolic resin, (C) a curing accelerator and (D) an inorganic filler as main components, characterized in that properties of a cured product formed by heating and curing the epoxy resin composition satisfy expressions, $a \geq = 10^R$ ($R=10\times(b+c)-1$, $300 \leq a \leq 20000$ and $0.15 \leq b+c \leq 0.50$ in which a denotes a flexural modulus (N/mm^2) at molding temperature, b denotes a cure shrinkage (%) and c denotes a heat shrinkage (%) of from molding temperature to room temperature.

13. (New) An area mounting semiconductor device formed by mounting semiconductor elements on one side of a printed circuit board or a metallic lead frame and encapsulating with an epoxy resin composition substantially only the side on which the semiconductor elements are mounted, wherein the epoxy resin composition comprises (A) an epoxy resin, (B) a phenolic resin, (C) a curing accelerator and (D) an inorganic filler as main components, properties of a cured product formed by heating and curing the epoxy resin composition satisfy expressions, $a \geq 10^R$ ($R=10x(b+c)-1$), $300 \leq a \leq 20000$ and $0.15 \leq b+c \leq 0.50$ in which a denotes a flexural modulus (N/mm^2) at molding temperature, b denotes a cure shrinkage (%) and c denotes a heat shrinkage (%) of from molding temperature to room temperature, and the value "a" is measured in accordance with JIS K 6911, and the value "b+c" is calculated from the formula,

$$\frac{\left(\begin{array}{c}\text{inner diameter of the}\\ \text{mold cavity at 175°C}\end{array}\right) - \left(\begin{array}{c}\text{outer diameter of the}\\ \text{disk cured product at 25°C}\end{array}\right)}{\left(\begin{array}{c}\text{inner diameter of the}\\ \text{mold cavity at 175°C}\end{array}\right)} \times 100$$